



SOT2033-2

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

15 October 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP91
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	08-07-2019
Manufacturer package code	98ASA01415D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.395	4.425	4.455	mm
package width	4.03	4.06	4.09	mm
seated height	-	0.129	0.146	mm
nominal pitch	-	0.15	-	mm
actual quantity of termination	-	91	-	



2 Package outline

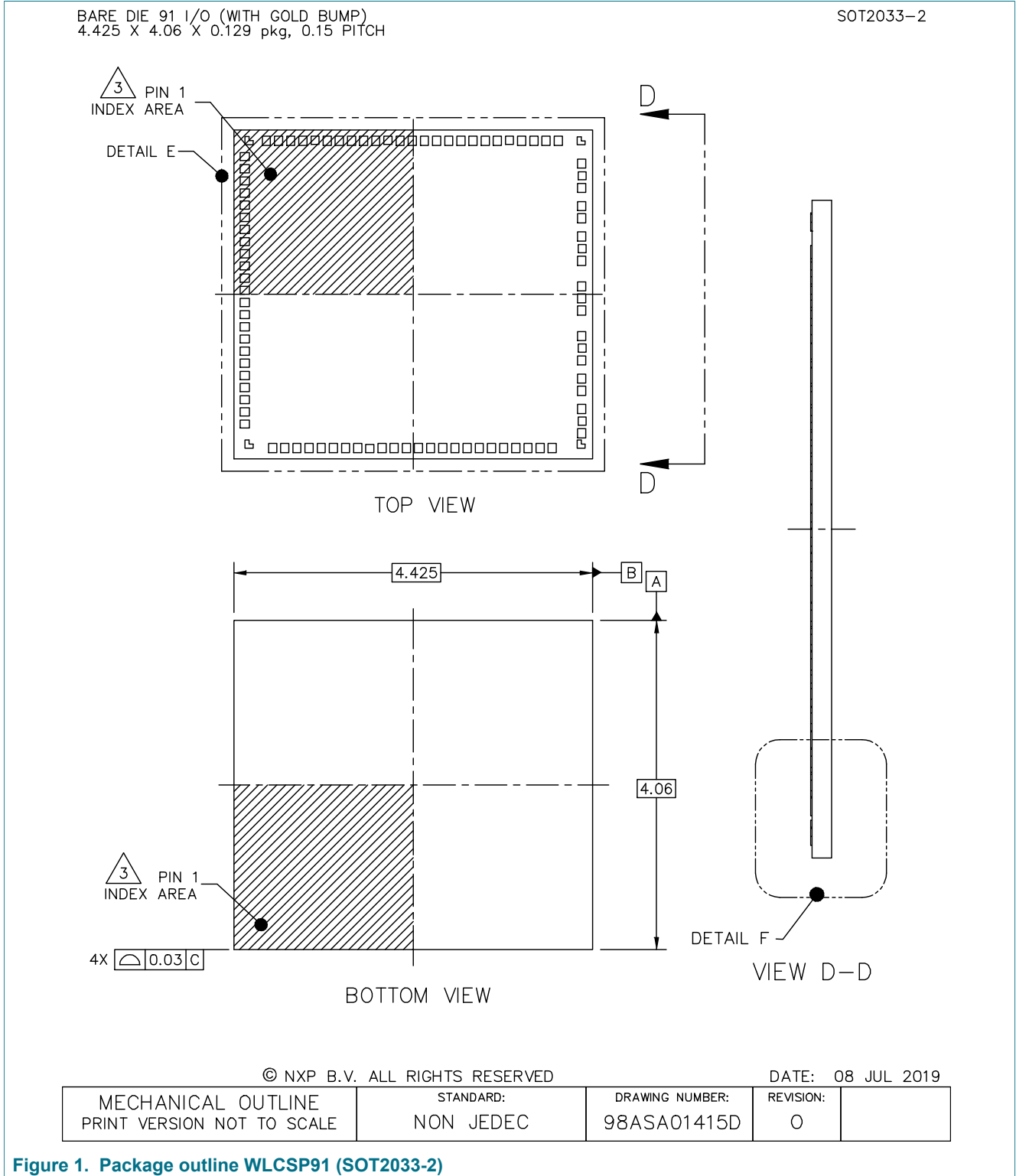


Figure 1. Package outline WLCSP91 (SOT2033-2)

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

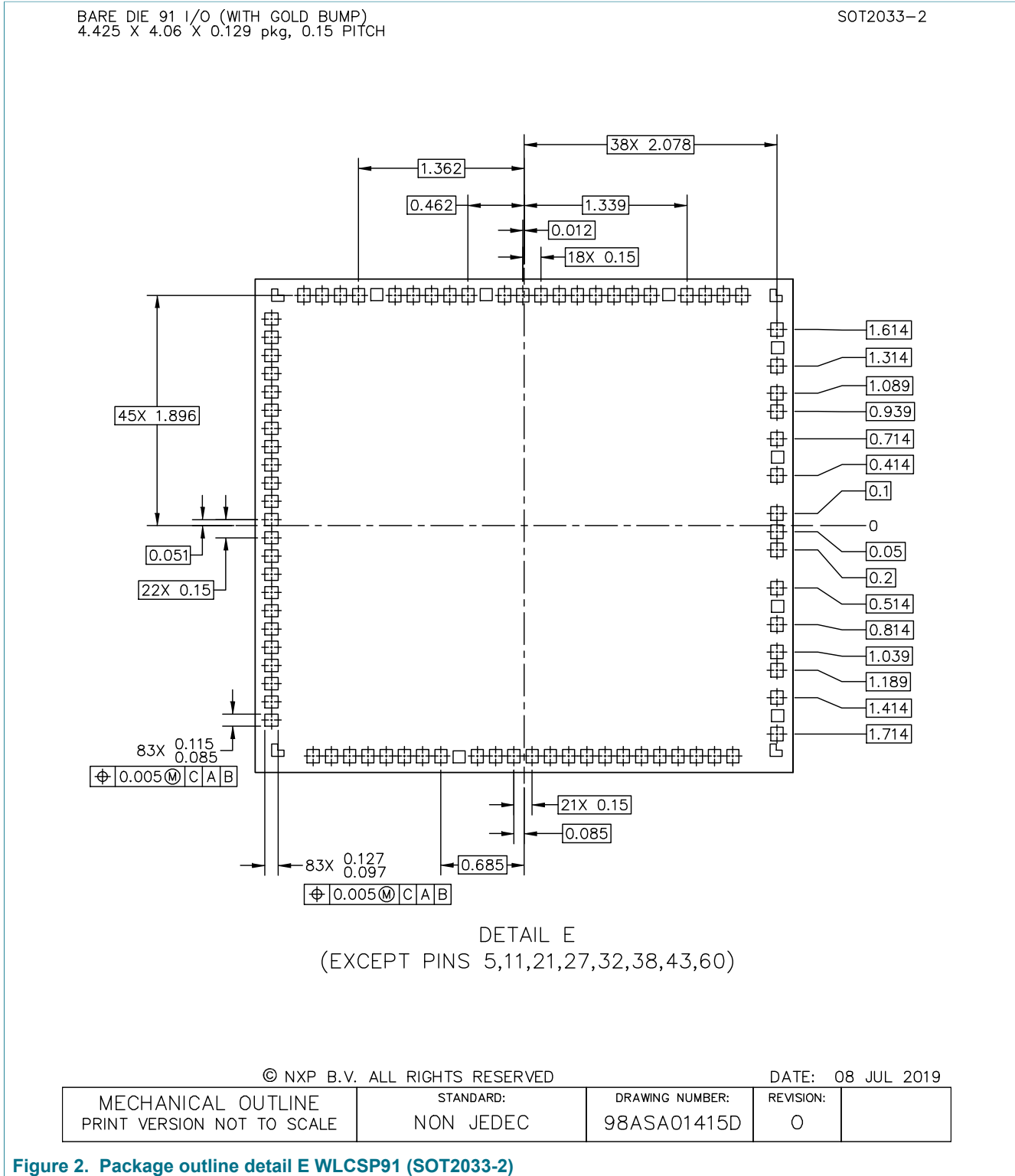


Figure 2. Package outline detail E WLCSP91 (SOT2033-2)

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

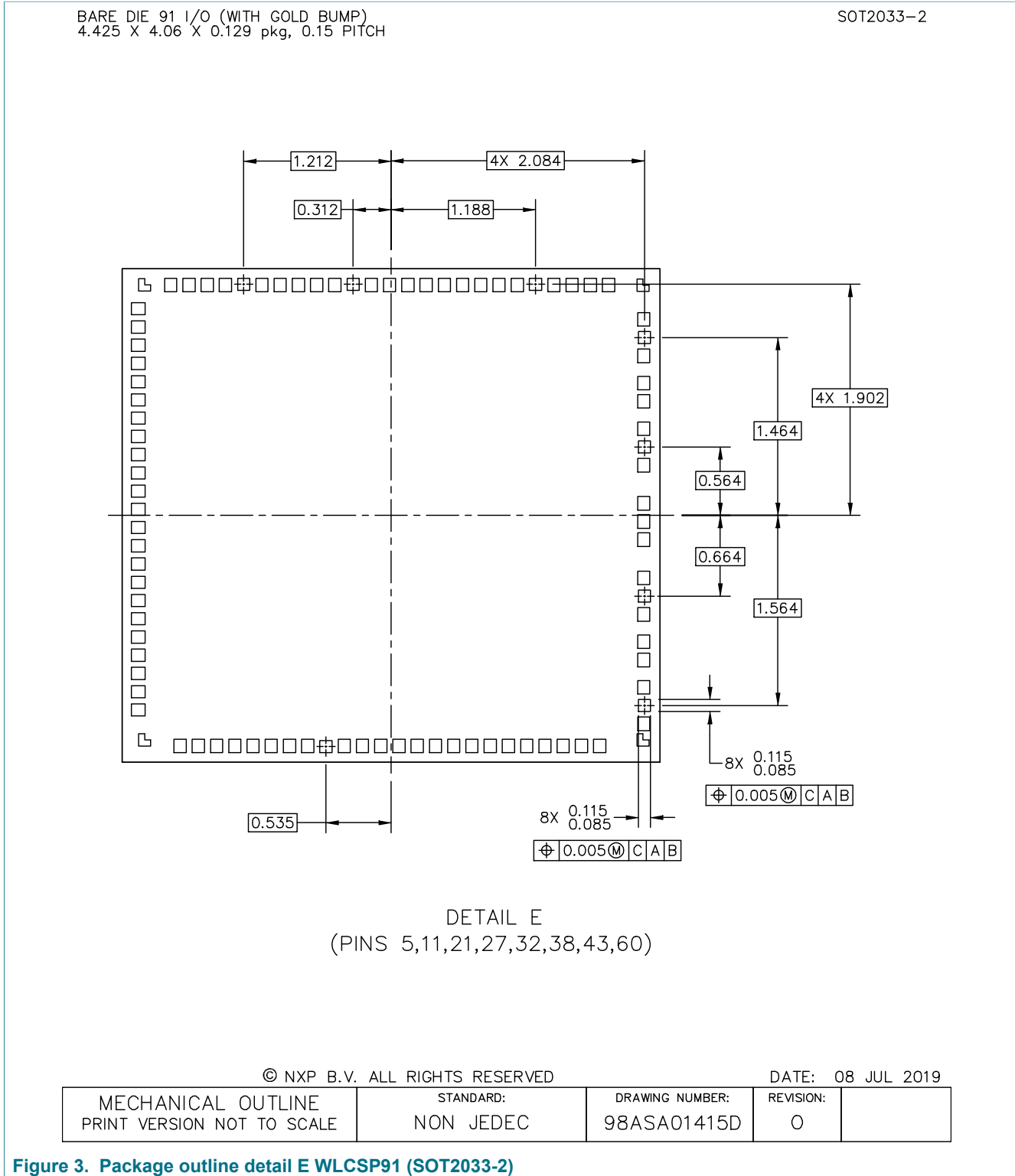


Figure 3. Package outline detail E WLCSP91 (SOT2033-2)

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

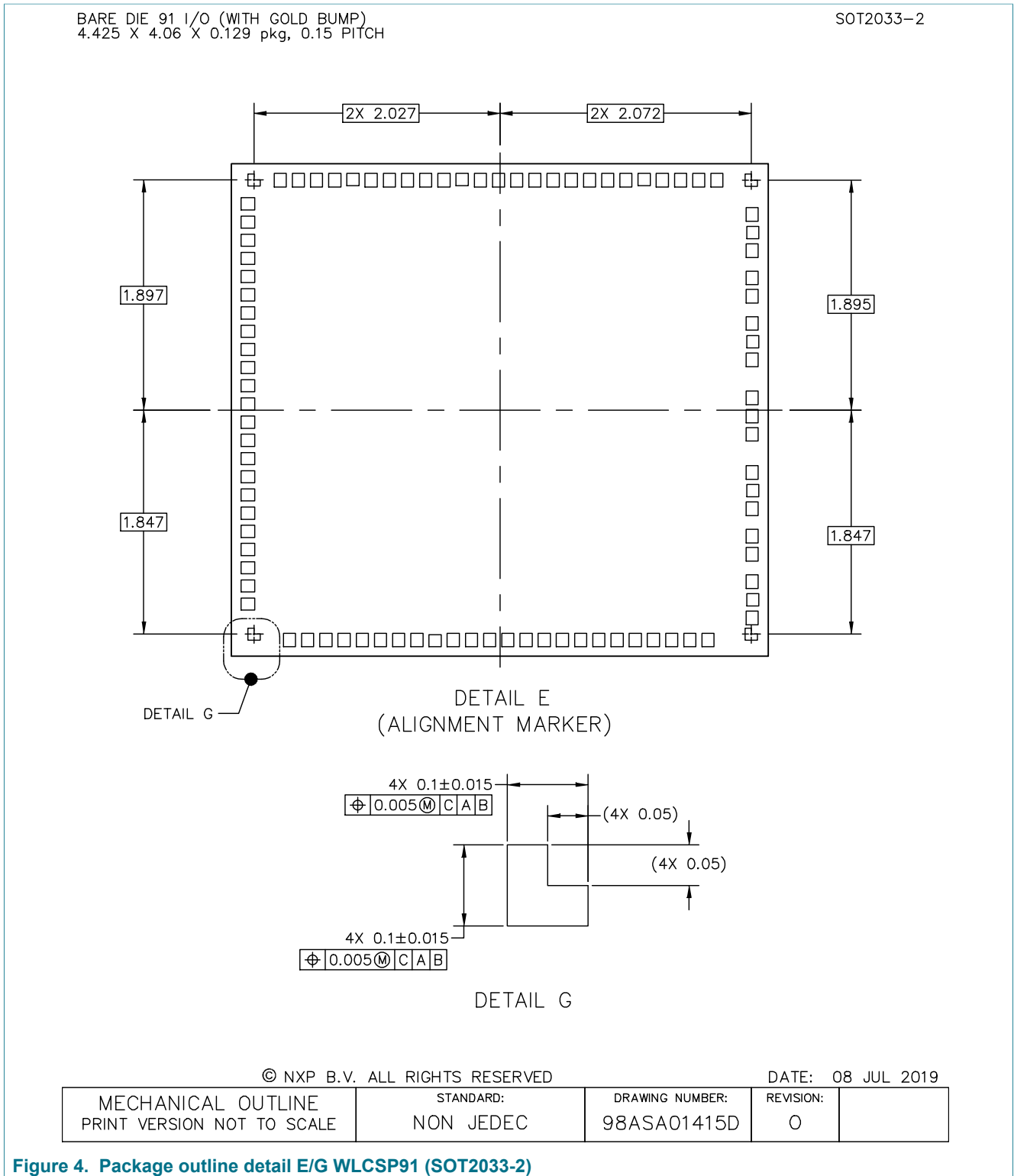


Figure 4. Package outline detail E/G WLCSP91 (SOT2033-2)

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

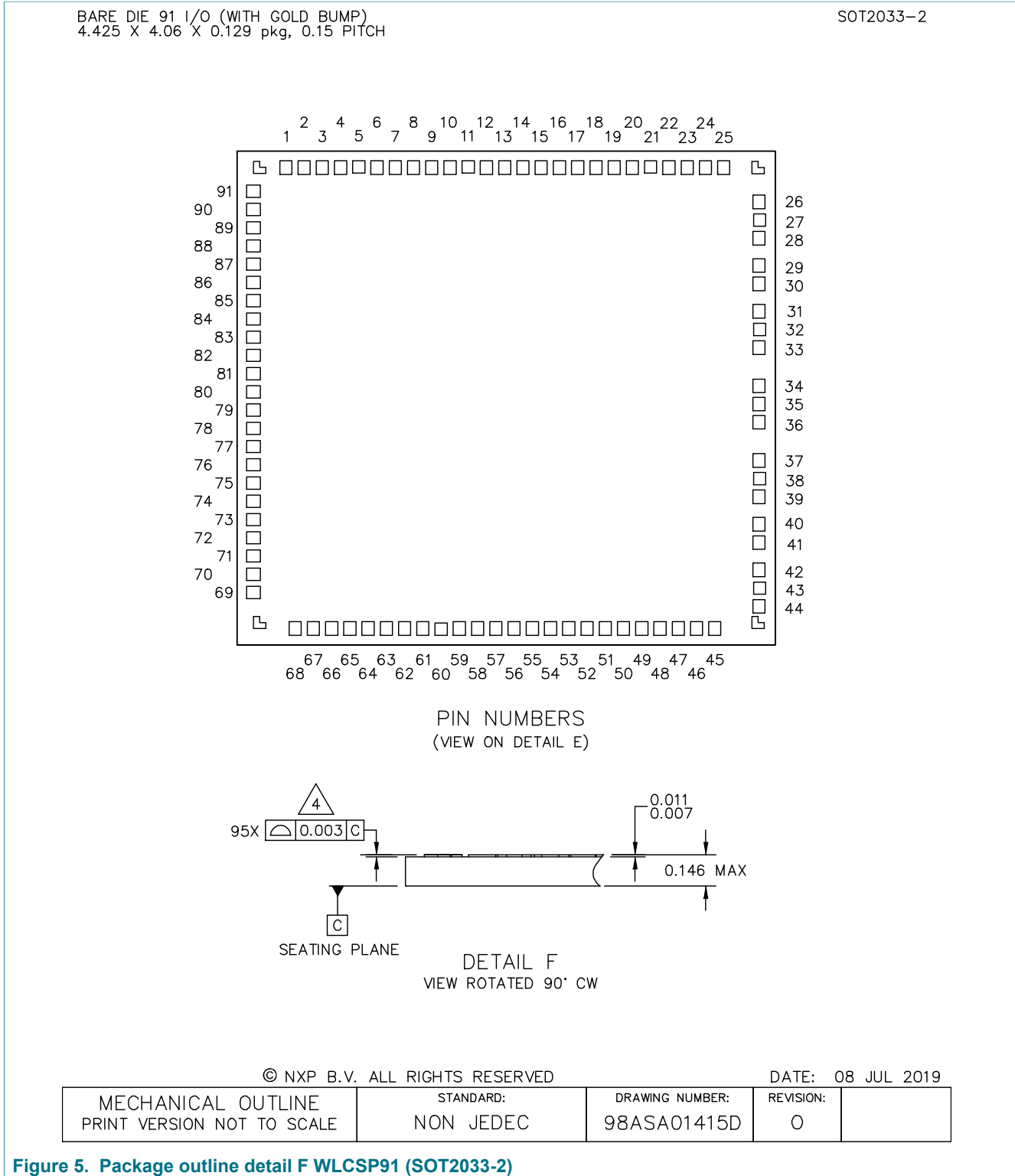


Figure 5. Package outline detail F WLCSP91 (SOT2033-2)

WLCSP91, wafer level chip scale package, 91 terminals with gold bump, 0.15 mm pitch, 4.425 mm x 4.06 mm x 0.129 mm body

BARE DIE 91 I/O (WITH GOLD BUMP)
4.425 X 4.06 X 0.129 pkg, 0.15 PITCH

SOT2033-2

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. DIMENSIONS APPLY TO ALL PINS.

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DATE: 08 JUL 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01415D	REVISION: 0	
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Figure 6. Package outline note WLCSP91 (SOT2033-2)

3 Legal information

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